

## **CHALLENGE 550-HT**

### **Non-Suspension Type Lapping/Polishing Slurry Additive for Recirculating Systems**

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**Challenge 550-HT** was developed for use in “high-speed recirculating” slurry application during lapping and polishing processes. Utilizing the energy of a high speed circulating pump, standard on most lapping machines, it evenly disperses aluminum oxide, cerium oxide, silicon carbide, boron carbide, and garnet abrasive. It also reduces abrasive usage by eliminating “hard-packing” of the abrasive in the slurry tank and the slurry lines. Using CHALLENGE 550-HT will also produce cleaner parts making the downstream cleaning line more efficient.

#### **Typical Properties:**

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Single and double sided lapping/polishing for recirculating systems

#### **Benefits:**

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- No scratching
- Less sub-surface damage
- No hard-packing
- Less abrasive waste
- Increased removal rate
- Easier post-lap cleaning
- Non-corrosive to machine

#### **Typical Properties:**

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pH	10.0
Conductivity Ms	0.3
Specific Gravity	1.02

#### **Directions:**

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CHALLENGE 550-HT is used at approximately 3- 5% (by weight) with deionized (DI) water or tap water that is not excessively hard. After CHALLENGE 550-HT is mixed with the water in the slurry tank, add the abrasive. The slurry will be ready for use almost immediately. Start grain loading 400 g/liter for a one-meter machine. Flow rate for the slurry should be approximately 300ml/minute for a one-meter machine.

#### **Additional Information:**

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CHALLENGE Products are available in 5-gallon pails and 55-gallon drums, F.O.B. Bethel, Connecticut, and also include: grinding fluids, sawing fluids, lapping/polishing slurry additives, rinse/wet storage additives and ultrasonic/megasonic detergents. Safety Data Sheets available upon request.